

## FDC638P P-Channel 2.5V Specified PowerTrench™ MOSFET

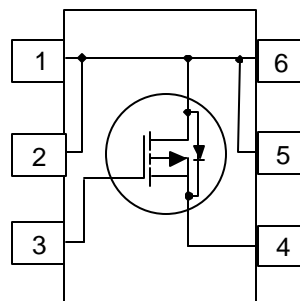
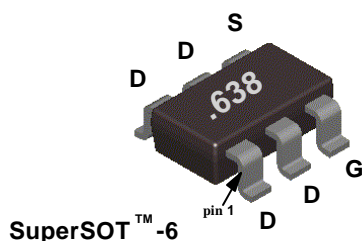
### General Description

This P-Channel 2.5V specified MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for battery power applications: load switching and power management, battery charging circuits, and DC/DC conversion.

### Features

- -4.5 A, -20 V.  $R_{DS(ON)} = 0.045 \Omega$  @  $V_{GS} = -4.5$  V  
 $R_{DS(ON)} = 0.065 \Omega$  @  $V_{GS} = -2.5$  V.
- Low gate charge (13nC typical).
- High performance trench technology for extremely low  $R_{DS(ON)}$ .
- SuperSOT™-6 package: small footprint (72% smaller than standard SO-8); low profile (1mm thick).



### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise note

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	-20	V
$V_{GSS}$	Gate-Source Voltage - Continuous	$\pm 8$	V
$I_D$	Drain Current - Continuous (Note 1a)	-4.5	A
	- Pulsed	-20	
$P_D$	Maximum Power Dissipation (Note 1a) (Note 1b)	1.6	W
		0.8	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	78	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	30	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25°C unless otherwise noted)							
Symbol	Parameter	Conditions	Min	Typ	Max	Units	
<b>OFF CHARACTERISTICS</b>							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = -250 μA	-20			V	
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	I <sub>D</sub> = -250 μA, Referenced to 25 °C		-18		mV/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0 V			-1	μA	
						-10	μA
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	V <sub>GS</sub> = 8 V, V <sub>DS</sub> = 0 V			100	nA	
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 0 V			-100	nA	
<b>ON CHARACTERISTICS</b> (Note 2)							
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-0.4	-0.9	-1.5	V	
ΔV <sub>GS(th)</sub> /ΔT <sub>J</sub>	Gate Threshold Voltage Temp. Coefficient	I <sub>D</sub> = -250 μA, Referenced to 25 °C		3		mV/°C	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -4.5 A		0.039	0.045	Ω	
					0.054		0.072
					0.057		0.065
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = -4.5 V, V <sub>DS</sub> = -5 V	-20			A	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -4.5 A		6.5		S	
<b>DYNAMIC CHARACTERISTICS</b>							
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		1240		pF	
C <sub>oss</sub>	Output Capacitance			270		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			100		pF	
<b>SWITCHING CHARACTERISTICS</b> (Note 2)							
t <sub>D(on)</sub>	Turn - On Delay Time	V <sub>DD</sub> = -5 V, I <sub>D</sub> = -1 A, V <sub>GS</sub> = -4.5 V, R <sub>GEN</sub> = 6 Ω		8	16	ns	
t <sub>r</sub>	Turn - On Rise Time			15	27	ns	
t <sub>D(off)</sub>	Turn - Off Delay Time			45	65	ns	
t <sub>f</sub>	Turn - Off Fall Time			30	50	ns	
Q <sub>g</sub>	Total Gate Charge		V <sub>DS</sub> = -10 V, I <sub>D</sub> = -4.5 A,		13	19	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -5 V		1.8		nC	
Q <sub>gd</sub>	Gate-Drain Charge			3		nC	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>							
I <sub>S</sub>	Continuous Source Diode Current				-1.3	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -1.3 A (Note 2)		-0.75	-1.2	V	
Notes:							
1. R <sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R <sub>θJC</sub> is guaranteed by design while R <sub>θCA</sub> is determined by the user's board design.							
a. 78°C/W when mounted on a 1 in <sup>2</sup> pad of 2oz Cu on FR-4 board.							
b. 156°C/W when mounted on a minimum pad.							
2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.							

## Typical Electrical Characteristics

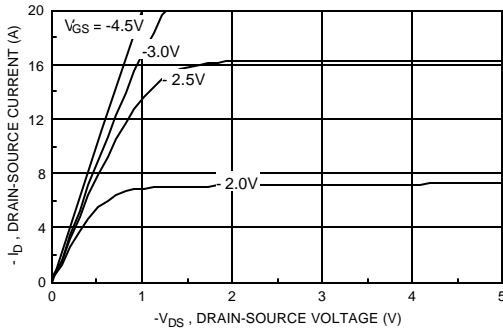


Figure 1. On-Region Characteristics.

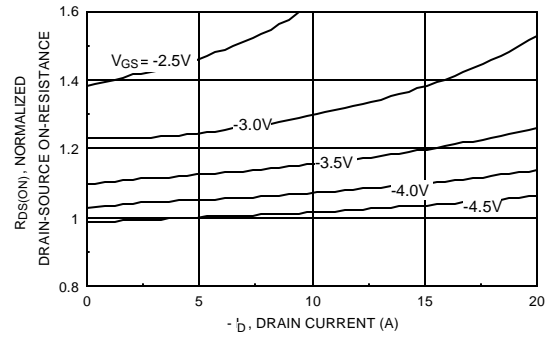


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

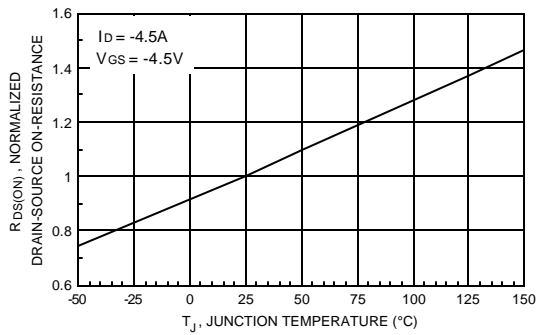


Figure 3. On-Resistance Variation with Temperature.

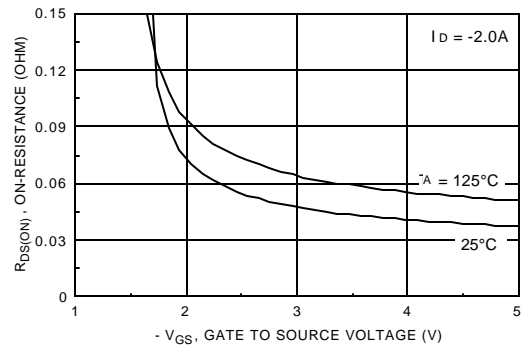


Figure 4. On Resistance Variation with Gate-to-Source Voltage.

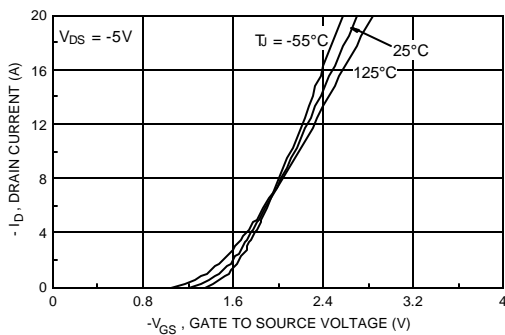


Figure 5. Transfer Characteristics.

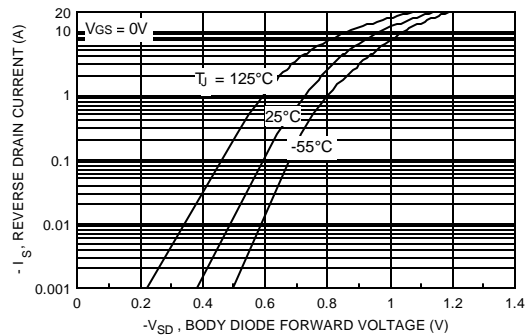


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Electrical Characteristics

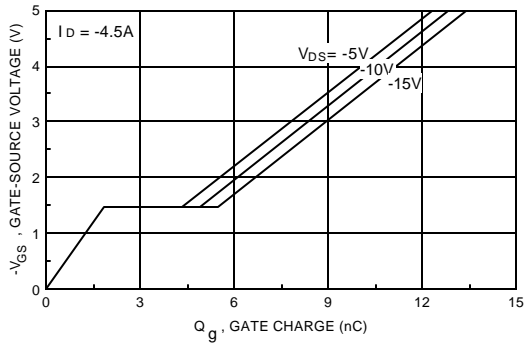


Figure 7. Gate Charge Characteristics.

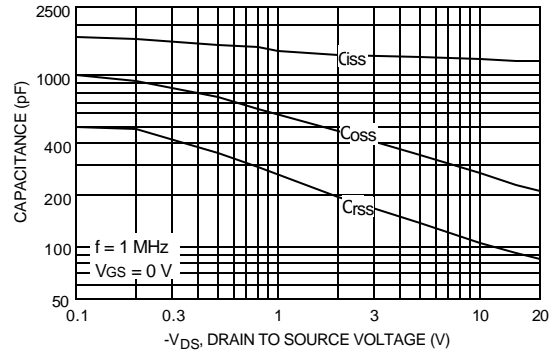


Figure 8. Capacitance Characteristics.

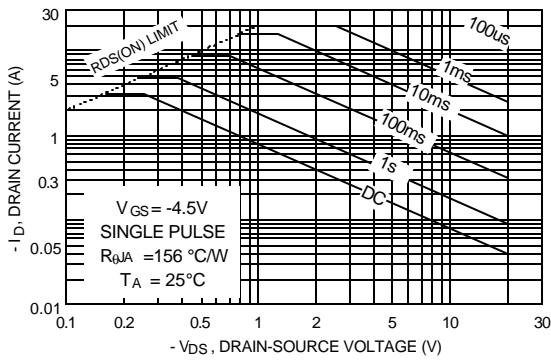


Figure 9. Maximum Safe Operating Area.

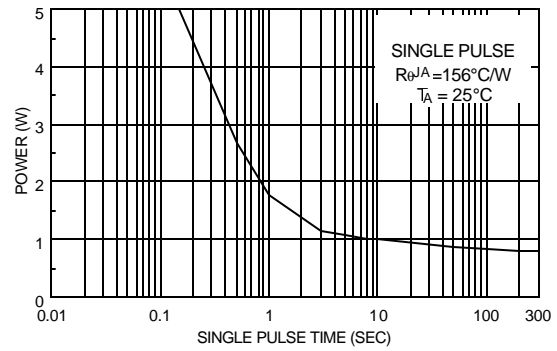


Figure 10. Single Pulse Maximum Power Dissipation.

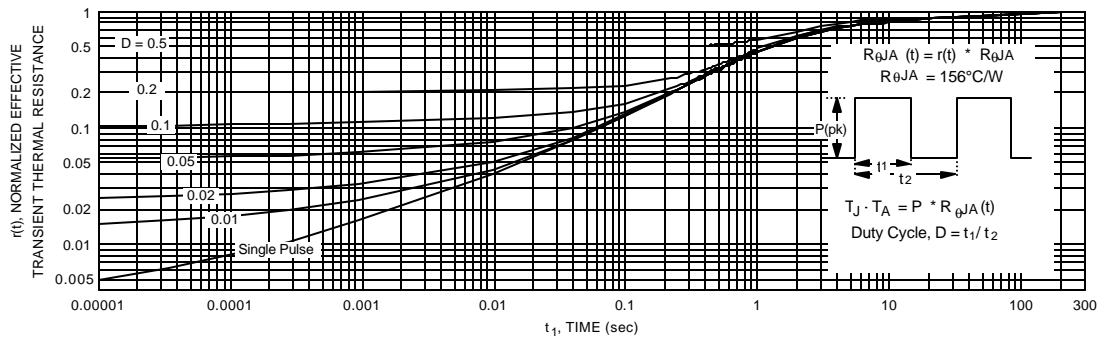


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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E <sup>2</sup> CMOS™	PowerTrench™	
FACT™	QST™	
FACT Quiet Series™	Quiet Series™	
FAST®	SuperSOT™-3	
FASTr™	SuperSOT™-6	
GTO™	SuperSOT™-8	
HiSeC™	TinyLogic™	

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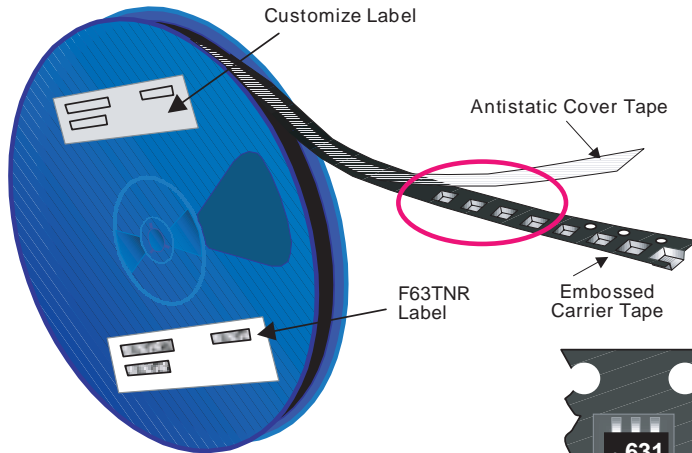
### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

# SuperSOT™-6 Tape and Reel Data and Package Dimensions



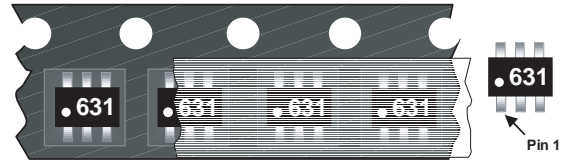
## SSOT-6 Packaging Configuration: Figure 1.0



### Packaging Description:

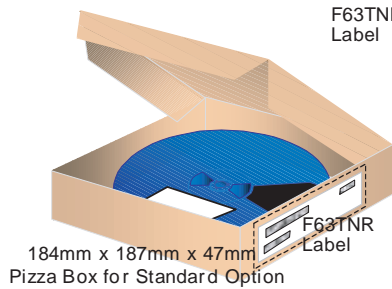
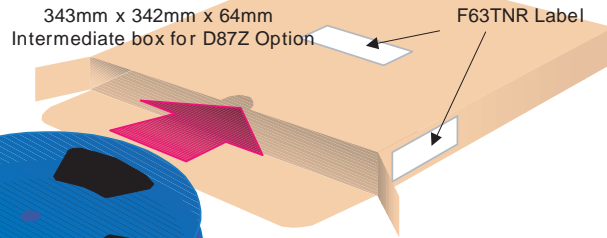
SSOT-6 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a pizza box (illustrated in figure 1.0) made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains three reels maximum. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.



### SSOT-6 Unit Orientation

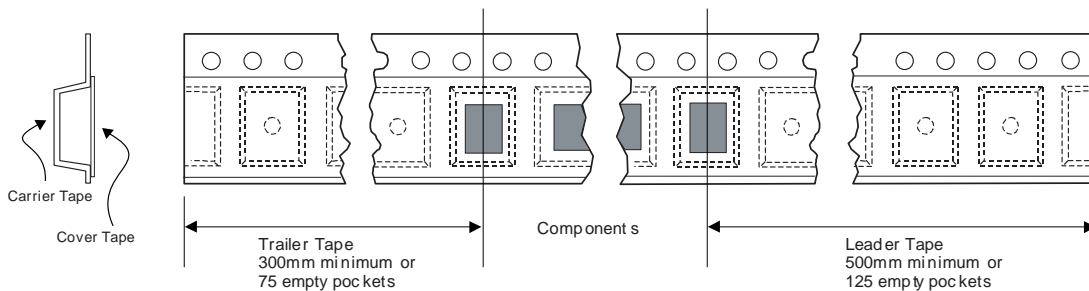
SSOT-6 Packaging Information			
Packaging Option	Standard (no flow code)	L99Z	D87Z
Packaging type	TNR	TNR	TNR
Qty per Reel/Tube/Bag	3,000	3,000	10,000
Reel Size	7" Dia	7" Dia	13"
Box Dimension (mm)	184x187x47	184x187x47	343x343x64
Max qty per Box	9,000	9,000	30,000
Weight per unit (gm)	0.0158	0.0158	0.0158
Weight per Reel (kg)	0.1440	0.1440	0.4700
Note/Comments		No marking required	



### F63TNR Label sample

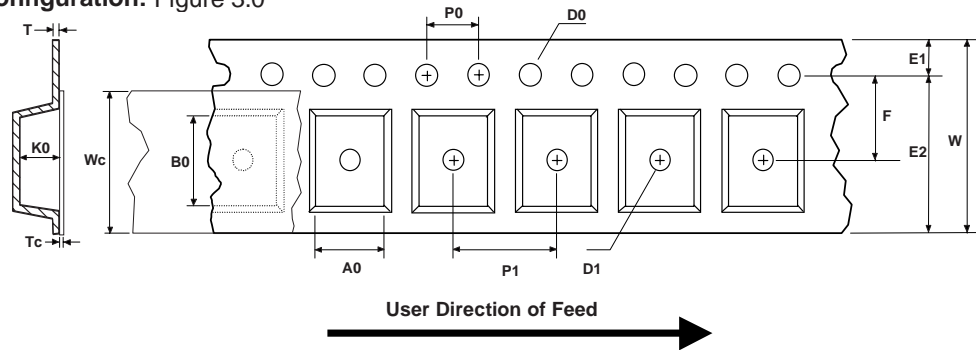


## SSOT-6 Tape Leader and Trailer Configuration: Figure 2.0



# SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued

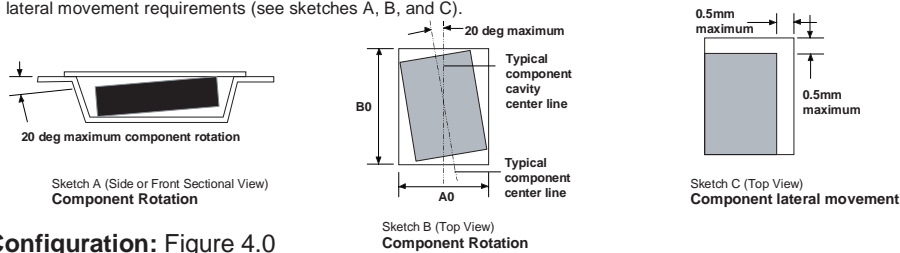
## SSOT-6 Embossed Carrier Tape Configuration: Figure 3.0



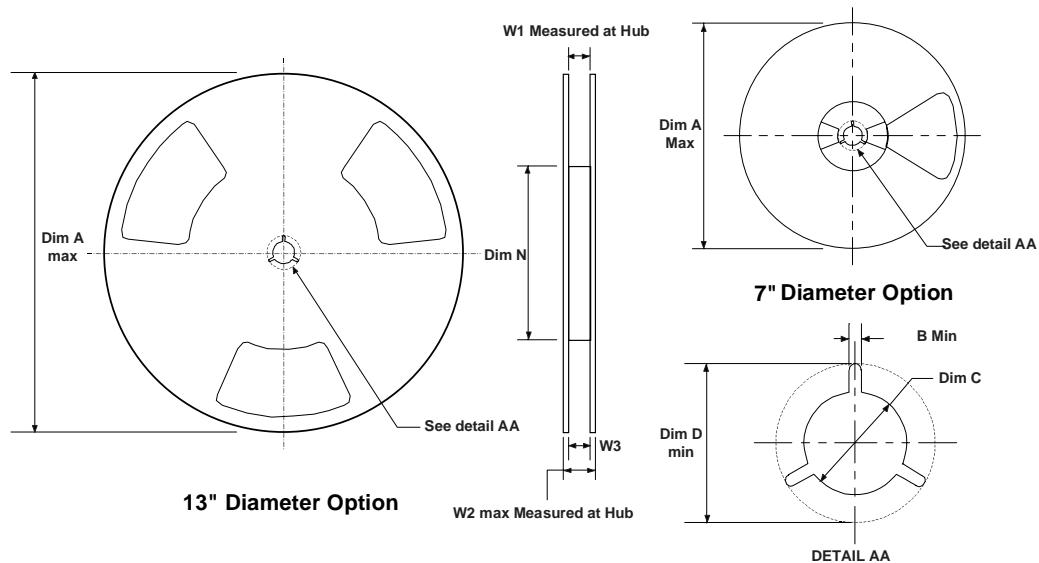
Dimensions are in millimeter

Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SSOT-6 (8mm)	3.23 +/-0.10	3.18 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



## SSOT-6 Reel Configuration: Figure 4.0

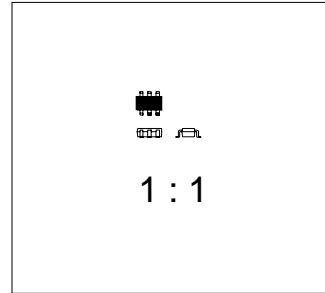
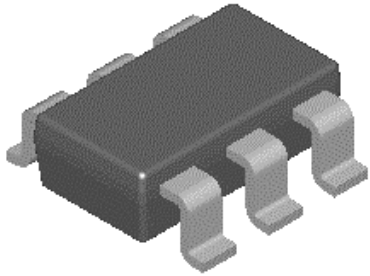


Dimensions are in inches and millimeters

Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

**SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued**

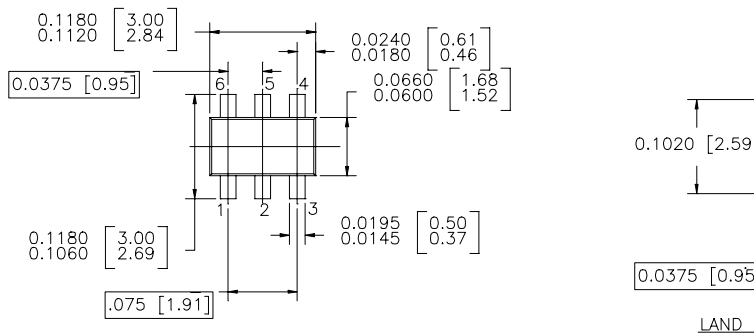
**SuperSOT™-6 (FS PKG Code 31, 33)**



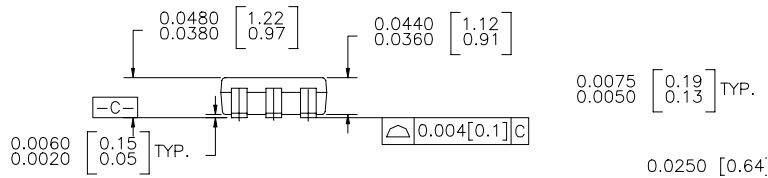
Scale 1:1 on letter size paper

Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.0158



CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICRONS (93.81 MICROMETERS)  
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

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